



Surface Mount Superfast Recovery Rectifier

Reverse Voltage – 50 to 600 V

Forward Current – 1 A

FEATURES

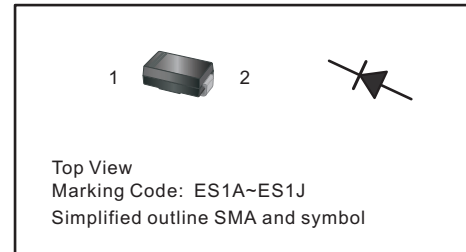
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.055g / 0.002oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

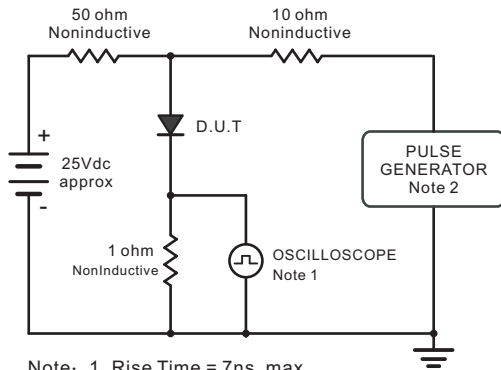
Parameter	Symbols	ES1A	ES1B	ES1C	ES1D	ES1E	ES1G	ES1J	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30							A
Maximum Forward Voltage at 1 A	V_F	1				1.25		1.70	V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25\text{ }^\circ\text{C}$ $T_a = 125\text{ }^\circ\text{C}$	I_R	5 100							μA
Typical Junction Capacitance at $V_R=4\text{V}$, $f=1\text{MHz}$	C_j	15							pF
Maximum Reverse Recovery Time ⁽¹⁾	t_{rr}	35							ns
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	75							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$

(1) Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$.

(2) P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 cm) copper pad areas.



Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

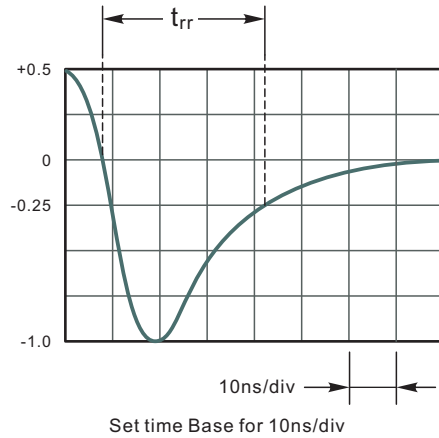


Fig.2 Maximum Average Forward Current Rating

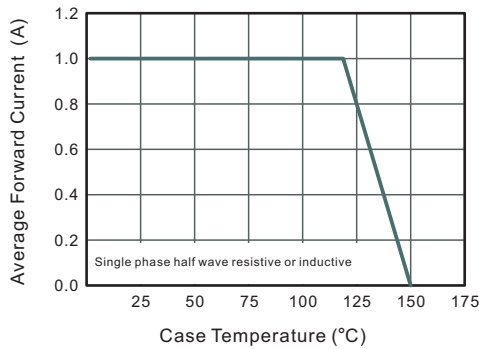


Fig.3 Typical Reverse Characteristics

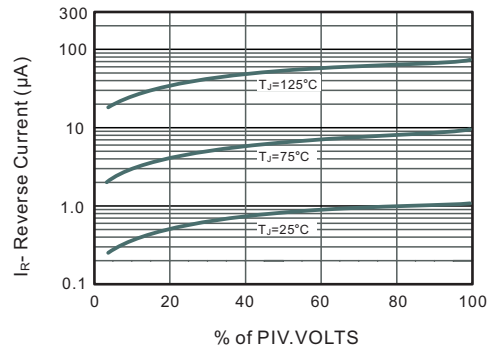


Fig.4 Typical Forward Characteristics

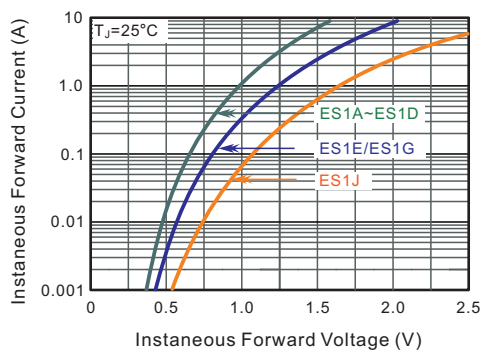


Fig.5 Typical Junction Capacitance

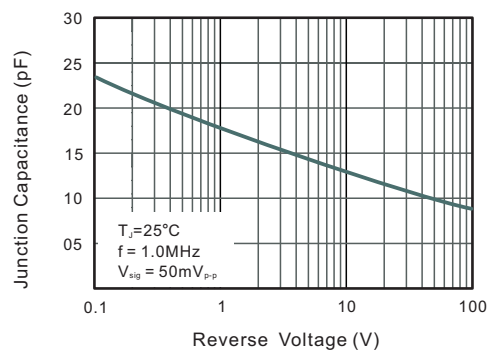
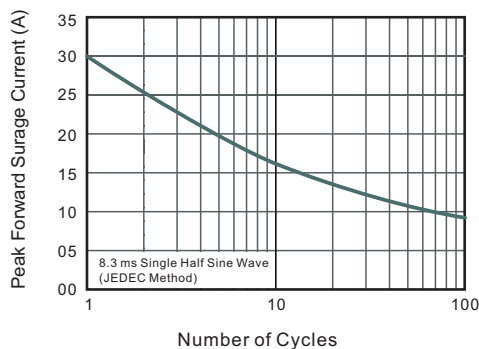


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current

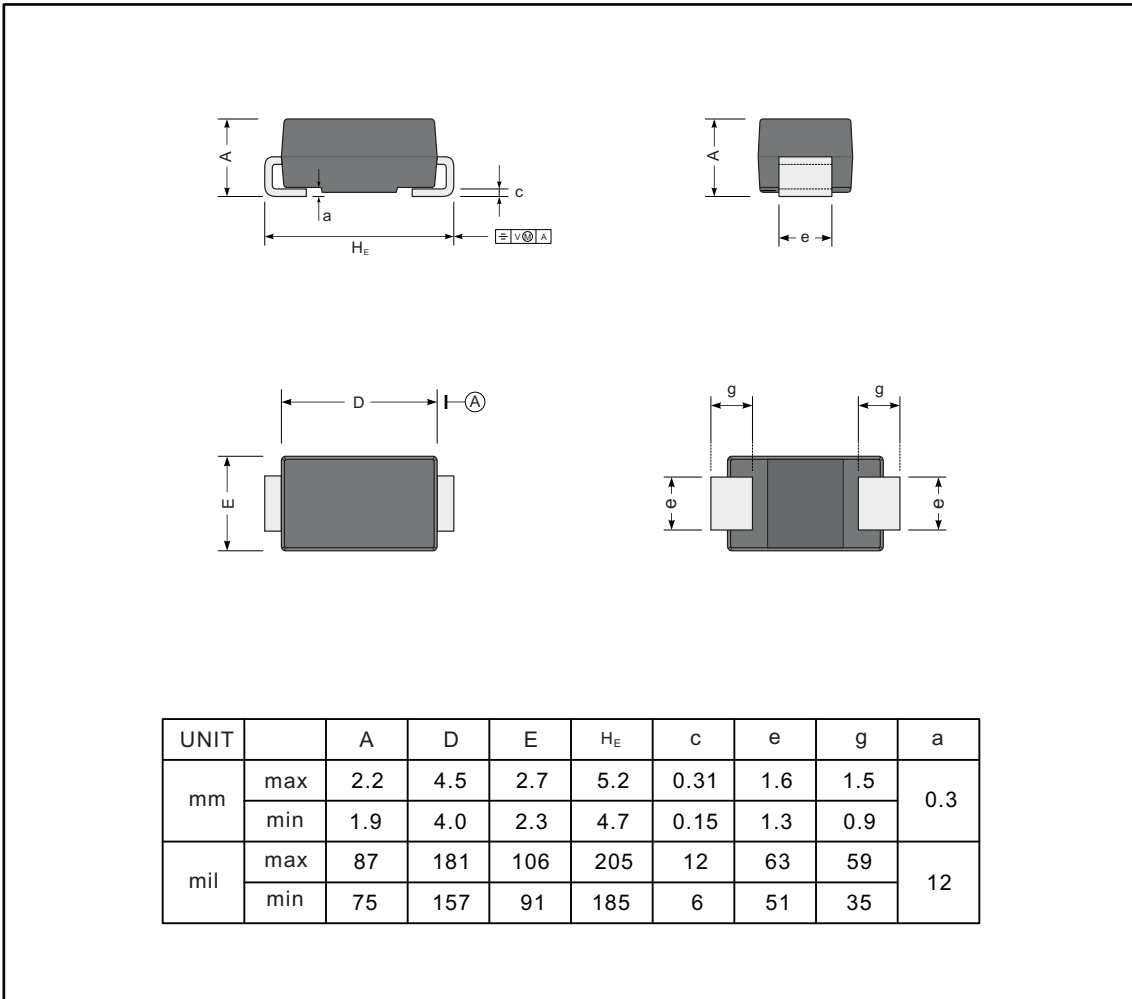




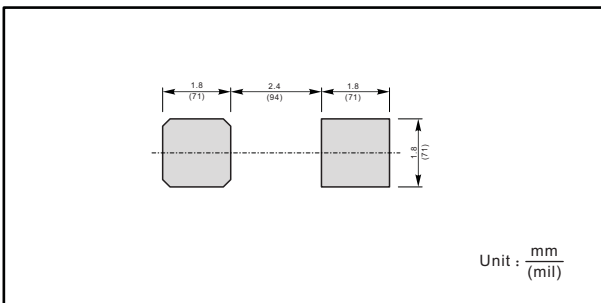
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMA



The recommended mounting pad size



Marking

Type number	Marking code
ES1A	ES1A
ES1B	ES1B
ES1C	ES1C
ES1D	ES1D
ES1E	ES1E
ES1G	ES1G
ES1J	ES1J

单击下面可查看定价，库存，交付和生命周期等信息

[>>JINGDAO\(晶导微\)](#)